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(71) Applicant (for all designated States except US): **KONINKLIJKE PHILIPS ELECTRONICS, N.V.** [NL/NL];
Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **FAN, Xuejun**
[CN/US]; P.O. Box 3001, Briarcliff Manor, NY
10510-8001 (US).

(74) Common Representative: **KONINKLIJKE PHILIPS ELECTRONICS, N.V.**; c/o **WAXLER, Aaron** P.O. Box
3001, Briarcliff Manor, NY 10510-8001 (US).

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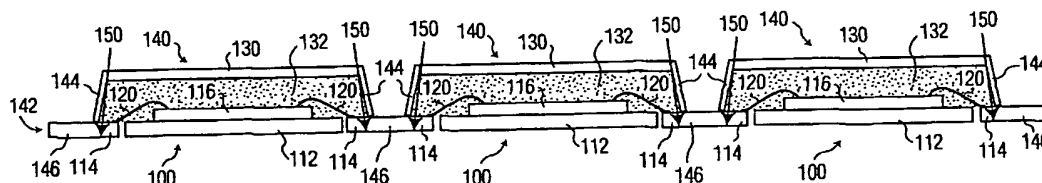
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(54) Title: **METHOD FOR PROVIDING DOUBLE-SIDED COOLING OF LEADFRAME-BASED WIRE-BONDED ELECTRONIC PACKAGES AND DEVICE PRODUCED THEREBY**



(57) Abstract: A method and apparatus for providing double-sided cooling of leadframe-based wire-bonded electronic packages. The method includes the steps of: positioning a plurality of heatslug members (140) over a corresponding plurality of electronic packages (100) formed on a leadframe strip (142), wherein each of the heatslug members includes a heatslug (130) and a plurality of legs (144) for supporting the heatslug over a respective one of the electronic packages; introducing a molding compound (132) between each heatslug member and its respective electronic package; curing the molding compound; and cutting the heatslug members and separating the electronic packages (100) from the leadframe strip, such that each electronic package includes a heatslug for cooling a first side of the electronic package.

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